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May 2014

# FCA36N60NF

# N-Channel SupreMOS<sup>®</sup> FRFET<sup>®</sup> MOSFET 600 V, 34.9 A, 95 m $\Omega$

#### **Features**

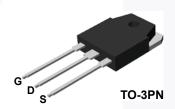
- $R_{DS(on)}$  = 80 m $\Omega$  (Typ.) @  $V_{GS}$  = 10V,  $I_D$  = 18 A
- Ultra Low Gate Charge (Typ. Q<sub>q</sub> = 86 nC)
- Low Effective Output Capacitance (Typ. C<sub>oss(eff.)</sub> = 338 pF)
- · 100% Avalanche Tested
- · RoHS Compliant

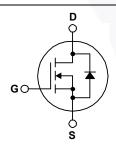
#### **Application**

- · Solar Inverter
- AC-DC Power Supply

#### Description

The SupreMOS® MOSFET is Fairchild Semiconductor's next generation of high voltage super-junction (SJ) technology employing a deep trench filling process that differentiates it from the conventional SJ MOSFETs. This advanced technology and precise process control provides lowest Rsp on-resistance, superior switching performance and ruggedness. SupreMOS MOSFET is suitable for high frequency switching power converter applications such as PFC, server/telecom power, FPD TV power, ATX power and industrial power applications. SupreMOS FRFET® MOSFET's optimized body diode reverse recovery performance can remove additional component and improve system reliability.





### **MOSFET Maximum Ratings** $T_C = 25^{\circ}C$ unless otherwise noted.

Symbol		Parameter	Parameter		Unit	
V <sub>DSS</sub>	Drain to Source Voltage			600	V	
V <sub>GSS</sub>	Gate to Source Voltage			±30	V	
I <sub>D</sub>	Drain Current	Continuous (T <sub>C</sub> = 25°C)		34.9	^	
	Drain Current	Continuous (T <sub>C</sub> = 100°C)	Continuous (T <sub>C</sub> = 100°C)		A	
I <sub>DM</sub>	Drain Current	Pulsed	(Note 1)	104.7	Α	
E <sub>AS</sub>	Single Pulsed Avalanche	Energy	nergy (Note 2)		mJ	
I <sub>AR</sub>	Avalanche Current		(Note 1)	12	Α	
E <sub>AR</sub>	Repetitive Avalanche En	titive Avalanche Energy		3.12	mJ	
dv/dt	MOSFET dv/dt			100	V/ns	
uv/ut	Peak Diode Recovery dv	r/dt	(Note 3)	50	V/IIS	
n	Dower Dissination	$(T_C = 25^{\circ}C)$		312	W	
$P_{D}$	Power Dissipation	Derate Above 25°C		2.6	W/°C	
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage T	emperature Range		-55 to +150	°С	
T <sub>L</sub>	Maximum Lead Tempera 1/8" from Case for 5 Sec	0,		300	°C	

#### **Thermal Characteristics**

Symbol	Parameter	FCA36N60NF	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	0.40	
$R_{\theta CS}$	Thermal Resistance, Case to Heat Sink, Typ.	0.24	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	40	

# **Package Marking and Ordering Information**

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FCA36N60NF	FCA36N60NF	TO-3PN	Tube	N/A	N/A	30 units

#### **Electrical Characteristics**

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Charac	cteristics					
BV <sub>DSS</sub>	Drain to Source Breakdown Voltage	$I_D = 1 \text{ mA}, V_{GS} = 0 \text{ V}, T_J = 25^{\circ}\text{C}$	600	-	-	V
ΔBV <sub>DSS</sub> / ΔΤ <sub>J</sub>	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 1 mA, Referenced to 25°C	-	0.60	-	V/°C
1	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 480 V, V <sub>GS</sub> = 0 V	-	-	10	^
IDSS	Zero Gate Voltage Drain Current	$T_{J} = 125^{\circ}C$	-	-	100	μА
I <sub>GSS</sub>	Gate to Body Leakage Current	V <sub>GS</sub> = ±30 V, V <sub>DS</sub> = 0 V	-	-	±100	nA

#### **On Characteristics**

V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$	3.0	3.7	5.0	V
R <sub>DS(on)</sub>	Static Drain to Source On Resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 18 A	-	80	95	mΩ
g <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 20 V, I <sub>D</sub> = 18 A	-	39	-	S

#### **Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance	V 400 V V 0 V	-	3191	4245	pF
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V, f = 1 MHz	-	145	195	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	1 - 1 1011 12	-\	5	8	pF
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> = 380 V, V <sub>GS</sub> = 0 V, f = 1 MHz	- \	81	-	pF
C <sub>oss</sub> eff.	Effective Output Capacitance	V <sub>DS</sub> = 0 V to 480 V, V <sub>GS</sub> = 0 V	- \	338	-	pF
Q <sub>g(tot)</sub>	Total Gate Charge at 10V	V <sub>DS</sub> = 380 V, I <sub>D</sub> = 18 A,	-	86	112	nC
$Q_{gs}$	Gate to Source Gate Charge	V <sub>GS</sub> = 10 V	-	16	-	nC
$Q_{gd}$	Gate to Drain "Miller" Charge	(Note 4)	-	36	-	nC
ESR	Equivalent Series Resistance (G-S)	f = 1 MHz	-	1.2	-	Ω

#### **Switching Characteristics**

	_						
t <sub>d(on)</sub>	Turn-On Delay Time			- /	27	64	ns
t <sub>r</sub>	Turn-On Rise Time	$V_{DD} = 380 \text{ V}, I_D = 18 \text{ A},$		-/	17	44	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{GS}$ = 10 V, $R_G$ = 4.7 $\Omega$		-	92	194	ns
t <sub>f</sub>	Turn-Off Fall Time		(Note 4)	-	4	18	ns

#### **Drain-Source Diode Characteristics**

$I_S$	Maximum Continuous Drain to Source Diode Forward Current		-	-	36	Α
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current		-	-	108	Α
$V_{SD}$	Drain to Source Diode Forward Voltage	V <sub>GS</sub> = 0 V, I <sub>SD</sub> = 18 A	-	-	1.2	V
t <sub>rr</sub>	Reverse Recovery Time	V <sub>GS</sub> = 0 V, I <sub>SD</sub> = 18 A,	-	166	-	ns
Q <sub>rr</sub>	Reverse Recovery Charge	$dI_F/dt = 100 A/\mu s$	-	1.3	-	μС

#### Notes

- 1. Repetitive rating: pulse-width limited by maximum junction temperature.
- 2.  $I_{AS}$  = 12 A,  $R_{G}$  = 25  $\Omega$ , starting  $T_{J}$  = 25°C.
- 3. I  $_{SD}$   $\leq$  36 A, di/dt  $\leq$  1200 A/ $\mu s$ , V  $_{DD}$  = 380 V, starting T  $_{J}$  = 25°C.
- 4. Essentially independent of operating temperature typical characteristics.

### **Typical Performance Characteristics**

Figure 1. On-Region Characteristics

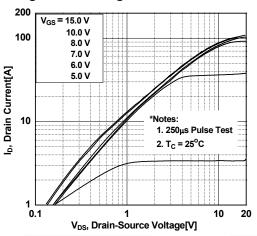


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage

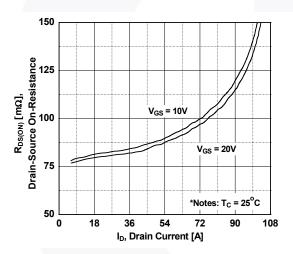


Figure 5. Capacitance Characteristics

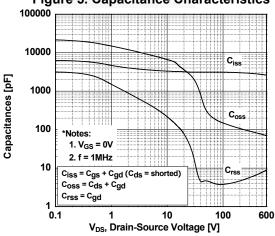


Figure 2. Transfer Characteristics

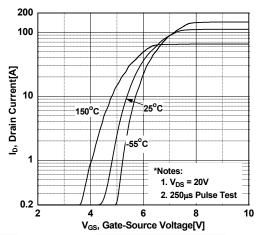


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

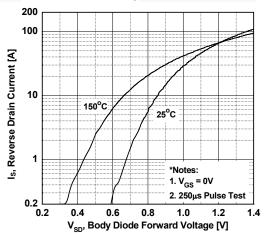
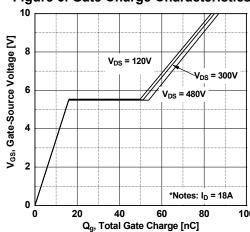


Figure 6. Gate Charge Characteristics



# **Typical Performance Characteristics** (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

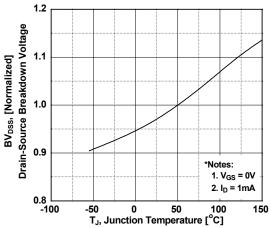


Figure 8. On-Resistance Variation vs. Temperature

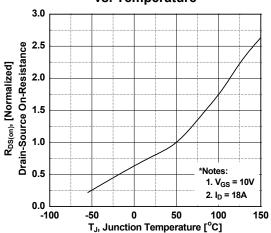


Figure 9. Maximum Safe Operating Area

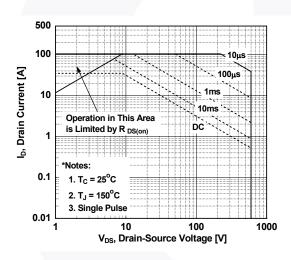


Figure 10. Maximum Drain Current vs. Case Temperature

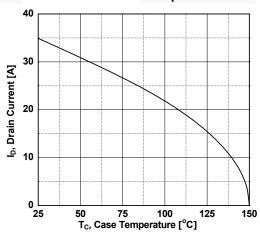
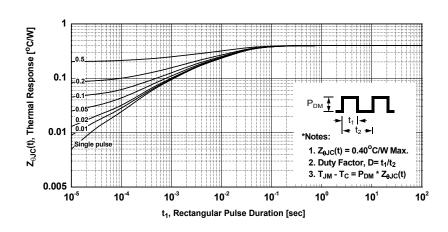


Figure 11. Transient Thermal Response Curve



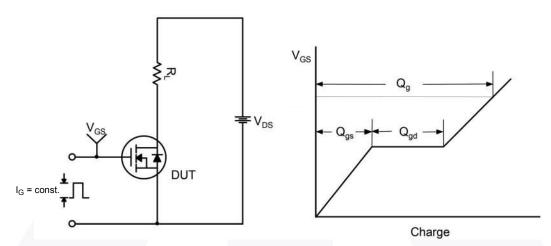


Figure 12. Gate Charge Test Circuit & Waveform

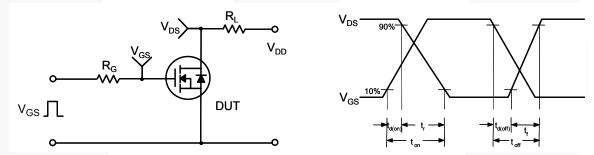


Figure 13. Resistive Switching Test Circuit & Waveforms

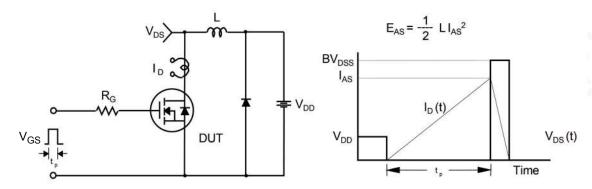


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms

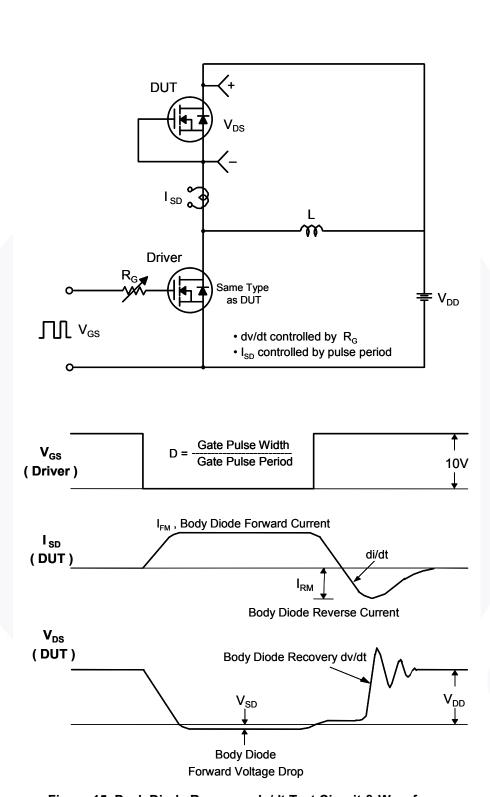
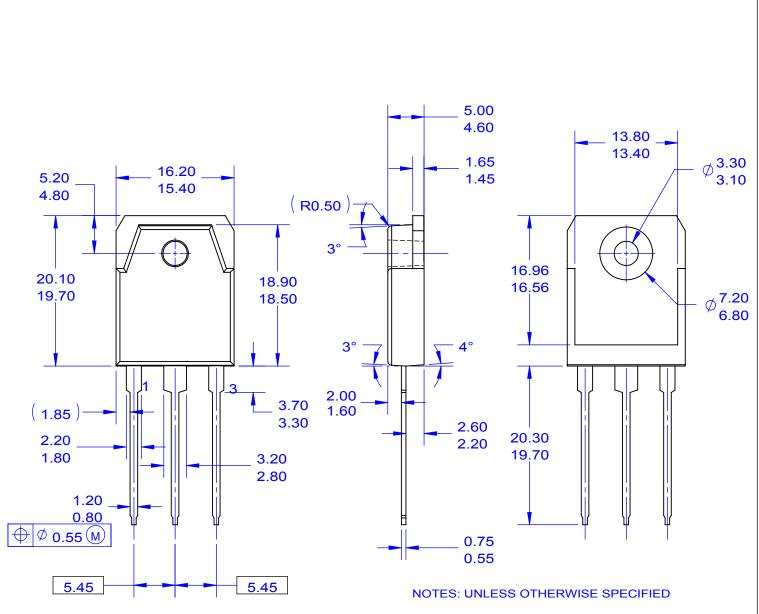
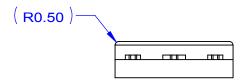


Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms





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